

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

- C¹
1. (Currently amended) A flexible matrix array device comprising
a thin film matrix circuit carried on the surface of a flexible substrate
which matrix circuit includes:
semiconductor devices arranged in a regular array and occupying
respective, discrete, first areas of the substrate, and
pixel electrodes correspondingly coupled to each of the
semiconductor devices and occupying respective second areas of the substrate;
wherein
selected regions of the substrate away from the areas occupied by the
semiconductor devices comprise areas of weakness at which the substrate is configured
such that flexing of the substrate occurs more readily at the second areas than at the first
areas.
 2. (Currently amended) A curved matrix array device comprising
a thin film matrix circuit carried on the surface of a substrate
which matrix circuit includes:
semiconductor devices arranged in a regular array and occupying
respective, discrete, first areas of the substrate, and
pixel electrodes correspondingly coupled to each of the
semiconductor devices and occupying respective second areas of the substrate;
wherein
the substrate is configured such that it comprises areas of weakness at selected
regions away from the semiconductor devices and
the curvature of the device is accommodated substantially by deformation at the
substrate at those regions the second areas.

C2

3. (Currently amended) A device according to Claim 1, wherein
the second areas of ~~weakness~~ comprise locally thinner regions of the substrate.

C3

4. (Original) A device according to Claim 3, wherein
the locally thinner regions are formed by selective etching of the substrate.
5. (Original) A device according to Claim 3, wherein
the substrate comprises a laminated structure with at least two layers and in which
one layer is patterned to form the locally thinner regions.

C4

6. (Currently amended) A device according to Claim 1, wherein
the second areas of ~~weakness~~ comprise areas of the substrate at which the material
of the substrate is rendered less stiff compared with the first areas of the substrate
occupied by the semiconductor devices.
7. (Currently amended) A device according to ~~any one of Claims~~ Claim 1, wherein
the substrate comprises polymer material.
8. (Currently amended) A device according to ~~any one of Claims~~ Claim 1, wherein
the second areas of ~~weakness~~ extend as include lines of ~~weakness~~ that facilitate
flexing of the substrate between the first areas of the substrate carrying the semiconductor
devices.

C5

9. (Currently amended) A device according to Claim 8, wherein
the semiconductor devices are arranged in an array of rows and columns and
wherein
the second areas of ~~weakness~~ comprise lines of ~~weakness~~ that facilitate flexing of
the substrate extending across the array between rows and/or columns of semiconductor
devices.

C6
10. (Currently amended) A device according to ~~any one of Claims~~ Claim 1, wherein the ~~discrete first areas of the substrate carrying the semiconductor devices are~~ thicker than the ~~remaining second areas of substrate~~.

C7
11. (Previously amended) A device according to claim 1, wherein the semiconductor devices each comprise a semiconductor film formed into an island.

12. (Previously amended) A device according to claim 1, wherein the semiconductor devices comprises thin film transistors.

C8
13. (Currently amended) A device according to claim 1, wherein the device comprises an active matrix display devices having an array of display pixels ~~and in which each semiconductor device is connected to a respective pixel electrode carried on the substrate~~.

C9
14. (Original) A device according to Claim 13, wherein the device comprises an active matrix liquid crystal display device which includes a further flexible substrate mounted to the substrate carrying the matrix circuit with liquid crystal material disposed between the substrates.

C10
15. (Currently amended) A device according to Claim 14, wherein the further substrate has lines of weakness that facilitate flexing formed therein.